

ABSTRACT

PHOTOSENSITIVE RESIN COMPOSITION, RESIST LAMINATE, AND CURED PRODUCT THEREOF (11)

The purpose of the present invention is to provide: a resin composition, a cured product of which has extremely low residual stress and exhibits excellent adhesion to a metal substrate such as a Pt, LT or Ta substrate after a wet heat test in the fields of semiconductors and MEMS/micromachine applications; a laminate of this resin composition; and a cured product of this resin composition or the laminate. The present invention is a photosensitive resin composition which contains an epoxy resin (A), a compound having a phenolic hydroxyl group (B) and a cationic photopolymerization initiator (C), and wherein: the epoxy resin (A) has a weighted average epoxy equivalent weight of 300 g/eq. or more; 20% by mass or more of the epoxy resin (A) is an epoxy resin represented by formula (1) and having an epoxy equivalent weight of 500-4,500 g/eq.; and the compound having a phenolic hydroxyl group (B) contains a phenolic compound having a specific structure.

